

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TIMOTHEE BLANQUART	05/04/2020
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17971265
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DATE SIGNED:	10/21/2022
Total Attachments: 2	
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Filing Date: January 18, 2019

Title: METHOD FOR DEPOSITING A GAP-FILL LAYER CONTAINING SILICON AND CARBON BY PLASMA-ASSISTED DEPOSITION

ASSIGNMENT

WHEREAS, TIMOTHEE BLANQUART, a citizen of France and a resident of Oud-Heverlee, Belgium,

(collectively, “WE” or “ASSIGNOR”) have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to METHOD FOR DEPOSITING A GAP-FILL LAYER CONTAINING SILICON AND CARBON BY PLASMA-ASSISTED DEPOSITION (collectively, the “INVENTIONS”) for which WE have executed and/or may execute one or more patent applications therefore; and

WHEREAS, ASM IP HOLDING B.V. (hereinafter “ASSIGNEE”), a corporation having a place of business at Versterkerstraat 8, Almere, 1322 AP, Netherlands, desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all patent applications therefore, and all patents that have granted or may be granted hereafter thereon, including, but not limited to, those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed and transferred, and by these presents do hereby sell, assign, convey and transfer, unto ASSIGNEE, its successors, its legal representatives and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefore that may have been filed or may be filed hereafter for said INVENTIONS (including but not limited Application No(s). 16/962,841, filed on January 18, 2019, as Docket No. PAT-JPN-0415-US-PCT (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known)) and all rights of priority under International Conventions, Treaties, and Agreements, all utility applications, national phase applications, utility model applications, divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications and design applications thereof, and all issued patents which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon;

AND WE DO HEREBY authorize and request any Official of any country or countries whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to ASSIGNEE, its successors, its legal representatives, and its assigns, in accordance with the terms of this instrument;

Application Serial No.: _____

Docket No.: PAT-JPN-0415-US-PCT

Filing Date: _____

Title: METHOD FOR DEPOSITING A GAP-FILL LAYER CONTAINING SILICON AND CARBON BY PLASMA-ASSISTED DEPOSITION

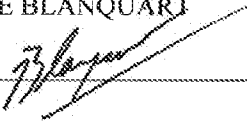
AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover and retain damages and any ongoing or prospective royalties to which WE may be entitled, or form any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives, and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries.

EXECUTED as of the date(s) below by ASSIGNOR:

TIMOTHEE BLANQUART

Signature



Date

2020.05.04